

Electronic Patent Application Fee Transmittal

Application Number:	10608606			
Filing Date:	27-Jun-2003			
Title of Invention:	METHOD FOR FABRICATING A PACKAGING DEVICE FOR SEMICONDUCTOR DIE AND SEMICONDUCTOR DEVICE INCORPORATING SAME			
First Named Inventor/Applicant Name:	Kong Weng Lee			
Filer:	Jay Kevin Malkin/Joy Reinhart			
Attorney Docket Number:	70030260-1			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790